

Disco DFG8540



Disco DFG8540 system is a fully automatic in-feed surface grinder. With its conventional two-spindle, three-chuck design, the DFG8540 is capable of performing both large diameter grinding and thin-finish grinding. The processing position of the grinding wheel coincides with the chuck table for each spindle for improved grinding performance.

OPTIONS AVAILABLE

Vacuum system with automatic fluid separation unit

Temperature control system for stabilizing process results

FEATURES

- Automated thinning up to 200mm diameter wafers
- Ultra-thin wafer handling to 100µm and less
- DBG option available and plasma-ready
- Flat/Notch alignment orientation
- Interior grind water nozzle
- Chuck/Spinner table
- Positioning and stopping system
- 2 air bearing grind spindles, 3 rotary-chuck tables



In-feed grinding w/wafer rotation